

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

SI2318DS-T1-E3-MS

Product specification

Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
40V	36mΩ	4A

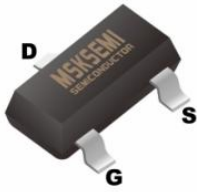
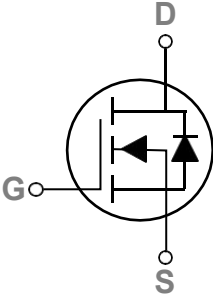

Features

- 40V, 4A, $R_{DS(ON)} = 36m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

Reference News

PACKAGE OUTLINE	N-Channel MOSFET	Marking
 SOT-23		

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_C = 25^\circ\text{C}$)	4	A
	Drain Current – Continuous ($T_C = 100^\circ\text{C}$)	3	A
I_{DM}	Drain Current – Pulsed ¹	16	A
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	1.56	W
	Power Dissipation – Derate above 25°C	0.012	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D = 1mA	---	0.04	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =40V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =32V , V _{GS} =0V , T _J = 125°C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance ³	V _{GS} = 10V , I _D =2A	---	36	45	mΩ
		V _{GS} =4.5V , I _D = 1.5A	---	45	70	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.6	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-4	---	mV/°C
gfs	Forward Transconductance	V _{DS} = 10V , I _D =4A	---	6	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2, 3}	V _{DS} =20V , V _{GS} =4.5V , I _D =3A	---	4.7	---	nC
Q _{gs}	Gate-Source Charge ^{2, 3}		---	0.45	---	
Q _{gd}	Gate-Drain Charge ^{2, 3}		---	1.65	---	
T _{d(on)}	Turn-On Delay Time ^{2, 3}	V _{DD} =20V , V _{GS} =4.5V , R _G =25Ω I _D = 1A	---	3.2	---	ns
T _r	Rise Time ^{2, 3}		---	8.6	---	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}		---	18	---	
T _f	Fall Time ^{2, 3}		---	6	---	
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , F= 1MHz	---	420	---	pF
C _{oss}	Output Capacitance		---	65	---	
C _{rss}	Reverse Transfer Capacitance		---	40	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	4	A
I _{SM}	Pulsed Source Current ³		---	---	8	A
V _{SD}	Diode Forward Voltage ³	V _{GS} =0V , I _S = 1A , T _J =25°C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} =0V, I _S = 1A , di/dt= 100A/μs T _J =25	---	20	---	ns
Q _{rr}	Reverse Recovery Charge		---	7.5	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

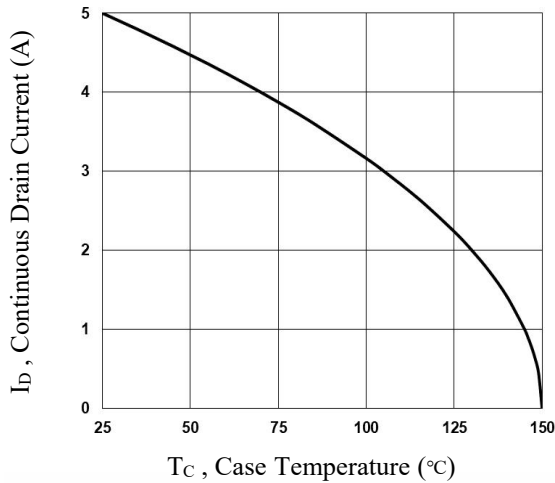


Fig.1 Continuous Drain Current vs. T_C

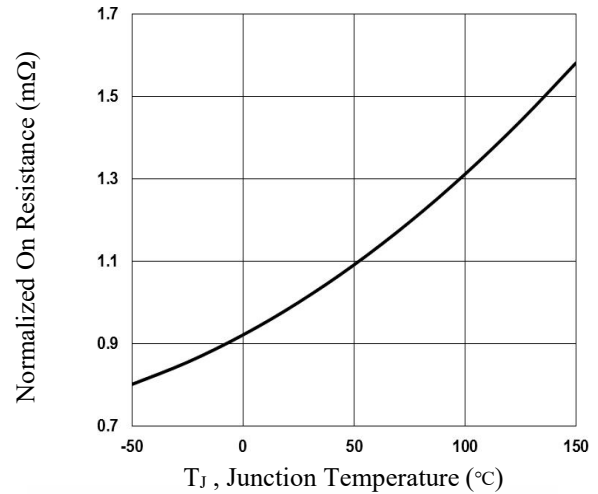


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

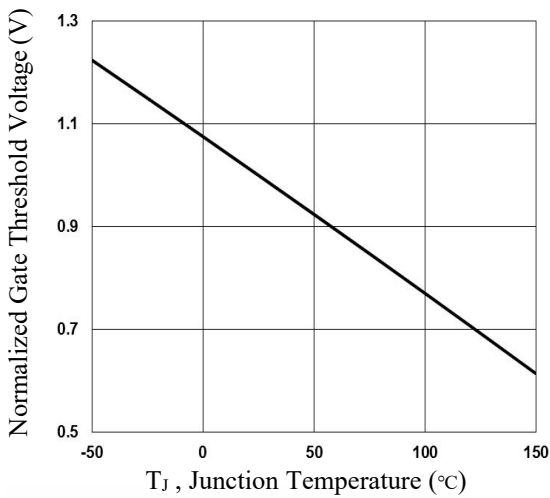


Fig.3 Normalized V_{th} vs. T_J

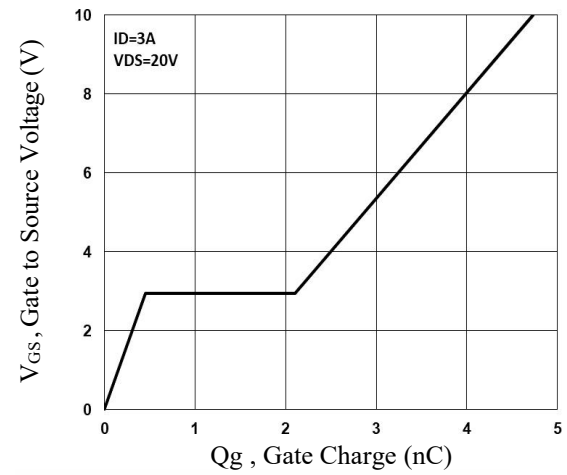


Fig.4 Gate Charge Waveform

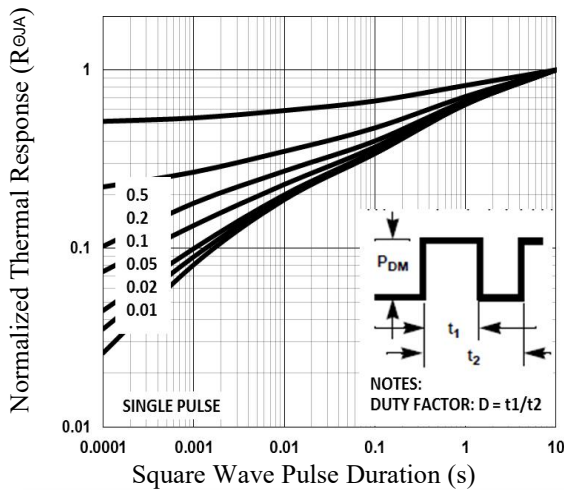


Fig.5 Normalized Transient Response

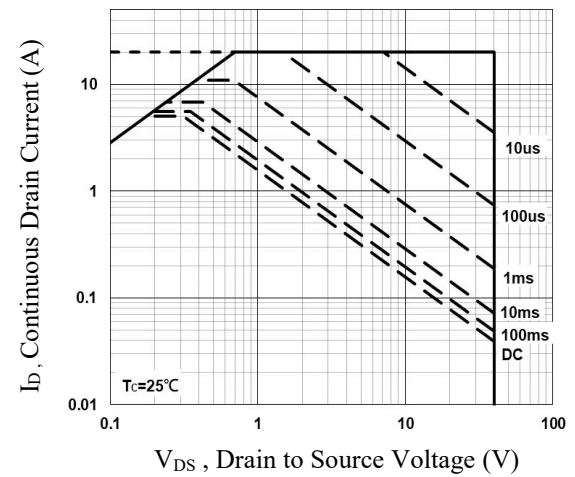
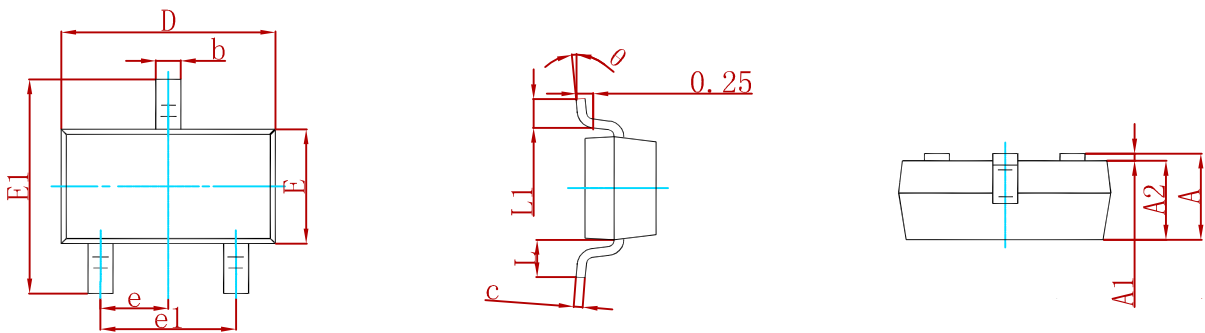


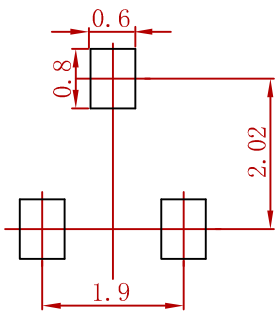
Fig.6 Maximum Safe Operation Area

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REELSPECIFICATION

P/N	PKG	QTY
SI2318DS-T1-E3-MS	SOT-23	3000

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